



# PROCOIL Inlays (ZiZa, WM, CuP)

## Highest durability and lifetime

Linxens wire-based PROCOIL inlay family, consisting of PROCOIL ZiZa, PROCOIL WM and PROCOIL CuP, provides card producers a durable and convenient solution for the manufacture of finished dual interface cards.

It ideally suits industry-standard manufacturing processes, which are based on fusing single substrate layers under pressure and high temperature to seal the wire antenna into the material of the card body.

Based on wire-embedding technology, the PROCOIL inlay antenna is embedded onto a thin substrate layer and available with wire meanders or copper pads as contact points for the dual interface chip contact module. Size and shape of the antenna can be adapted according to the performance requirements.

PROCOIL inlays are offered in customized sheet formats meeting customer specific card lamination requirements and are available in a wide range of different colors.

Linxens production site of PROCOIL inlays is compliant with MasterCard's Card Quality Management (CQM) requirements.

Antenna	Thickness	Operating Temperature	Available for following ICs
ID1, ID1/2, ID2/3	150 - 400 µm	max. 580 x 705 mm	Infineon NXP

Other antenna sizes available upon request.

RFID

**Overview**

**Operating Frequency**  
• 13.56 MHz

**Material**  
• PVC  
• Other substrates upon request

**International Standards**  
• ISO 14443

**Application Area**  
Dual Interface Cards for:  
• Contactless Payment

**Benefits**  
• Customized sheet formats  
• Available in different colors  
• Suitable for regular hot lamination